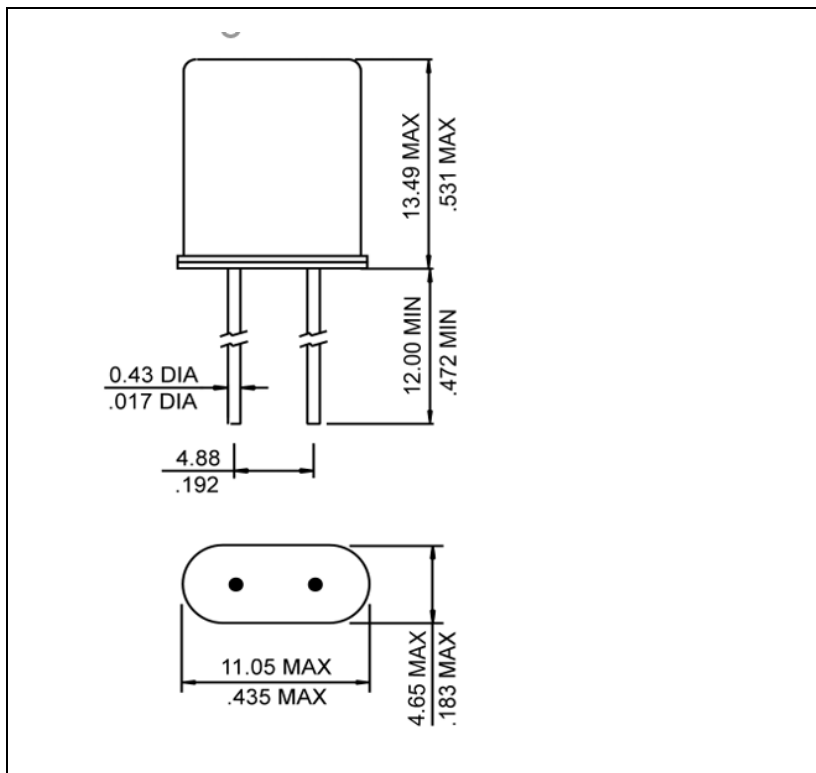


● **SPECIFICATIONS**

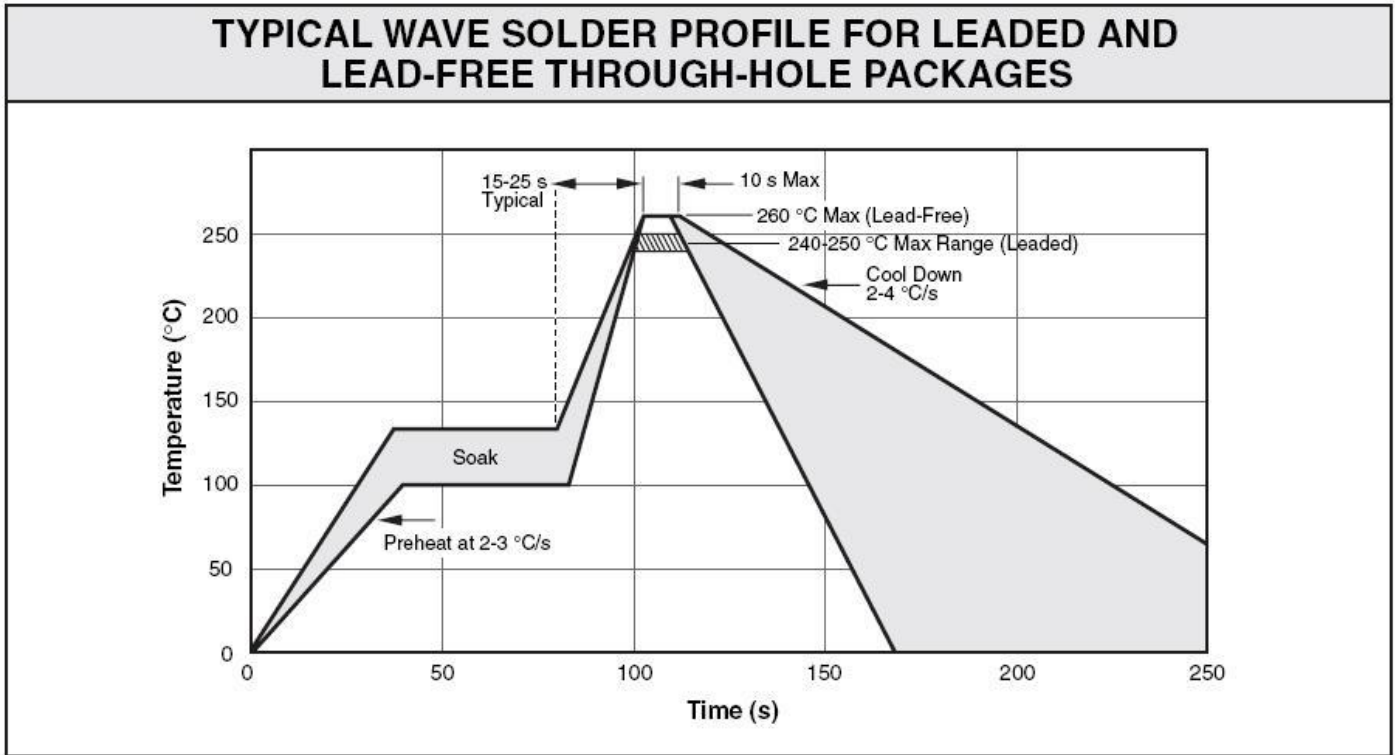
PARAMETER	VALUE
NOMINAL FREQUENCY	3.579545 MHz
MODE OF OSCILLATION	Fundamental
FREQUENCY TOLERANCE AT 25°C	±30 ppm max
FREQUENCY STABILITY OVER TEMPERATURE	±50 ppm max
OPERATING TEMPERATURE RANGE	-20°C to +70°C
STORAGE TEMPERATURE RANGE	-55°C to +125°C
AGING, MAXIMUM	±5 ppm per year
LOAD CAPACITANCE	18 pF
EQUIVALENT SERIES RESISTANCE	180 Ω max
SHUNT CAPACITANCE	7 pF max
DRIVE LEVEL	1 mW max

● **MECHANICAL SPECIFICATION**



NOTE: Through hole device can withstand 245°C soldering by terminals only

● WAVE SOLDER PROFILE



Wave Solder profile		
Profile Feature	SnPb eutectic	Pb-Free
Average ramp-up rate	~200°C/second	~200°C/second
Heating Rate during preheat	typical 1-2°/second max 4°/second	typical 1-2°/second max 4°/second
Final preheat temperature, T _S	~130°C	~130°C
Peak temperature, T _P	235°C	260°C
Time within +0°C / -5°C of actual temperature, t _P	10 seconds	10 seconds
Ramp-down rate	5°C/second max.	5°C/second max.

NOTE: This document should serve as recommendation only. Other parameters may also affect soldering, this profile does not guarantee absolute success. Soldering profile should be determined by the equipment manufacturer and customers' process engineer.

● ENVIRONMENTAL

PARAMETER	VALUE
MOISTURE SENSITIVITY LEVEL	1
RoHS	Compliant
REACH SVHC	Compliant
HALOGEN-FREE	Compliant
ESD CLASSIFICATION LEVEL	N/A
TERMINATION FINISH	Sn



MARKING

3.579
18pF
Ryyxxww

x – Internal Production ID code
y – Year code
w – Week code

YEAR CODE	
Year	Code
2011	1
2012	2
2013	3
2014	4
2015	5
2016	6
2017	7
2018	8
2019	9

ALPHA WEEK CODE TABLE					
Week	Code	Week	Code	Week	Code
1	a	19	s	37	K
2	b	20	t	38	L
3	c	21	u	39	M
4	d	22	v	40	N
5	e	23	w	41	O
6	f	24	x	42	P
7	g	25	y	43	Q
8	h	26	z	44	R
9	i	27	A	45	S
10	j	28	B	46	T
11	k	29	C	47	U
12	l	30	D	48	V
13	m	31	E	49	W
14	n	32	F	50	X
15	o	33	G	51	Y
16	p	34	H	52	Z
17	q	35	I		
18	r	36	J		

APPROVAL

DRAWN BY:	K.Jackson, Sept 11, 2014
APPROVED BY:	K.Jackson, Sept 11, 2014
REVISION:	A, Initial Release B. AG, January 11, 2019, update solder profile to wave solder

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